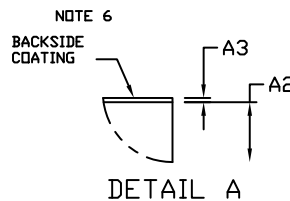
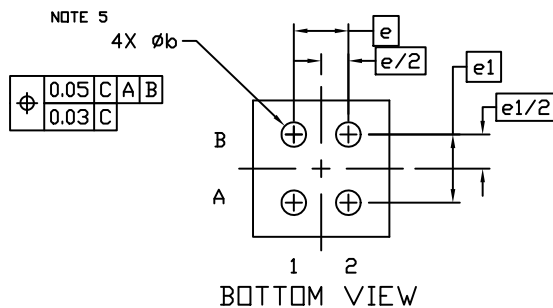
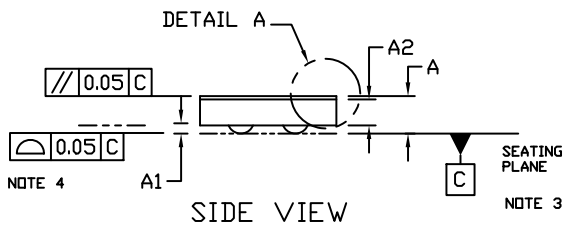
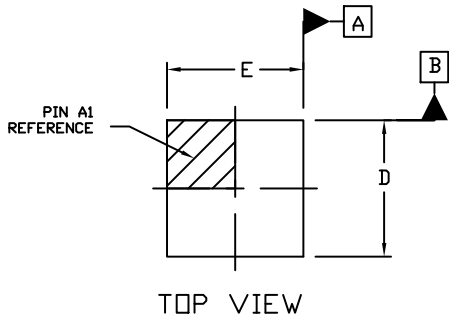




WLCSP4 1.00x1.00x0.30  
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ISSUE O

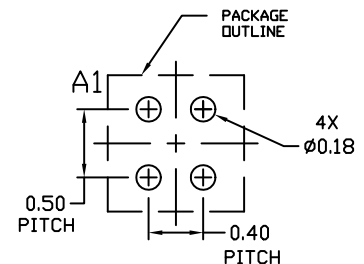
DATE 02 JAN 2019



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DATUM C, THE SEATING PLANE, IS DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
4. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. DIMENSION *b* IS MEASURED AT THE MAXIMUM CONTACT BALL DIAMETER PARALLEL TO DATUM C.

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	---	---	0.30
A1	0.040	0.060	0.080
A2	0.190 REF		
A3	0.025 REF		
<i>b</i>	0.16	0.18	0.20
D	0.98	1.00	1.02
E	0.98	1.00	1.02
<i>e</i>	0.40 BSC		
<i>e</i> 1	0.50 BSC		



GENERIC MARKING DIAGRAM\*



- X = Specific Device Code
- Y = Year
- W = Work Week

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "µ", may or may not be present. Some products may not follow the Generic Marking.

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